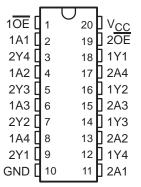
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- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Small-Outline (DW, NS), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

DGV, DW, NS, OR PW PACKAGE (TOP VIEW)



description

This octal buffer/line driver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH244 is organized as two 4-bit line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH244 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each buffer)

INPU	JTS	OUTPUT			
OE	Α	Υ			
L	Н	Н			
L	L	L			
Н	Χ	Z			

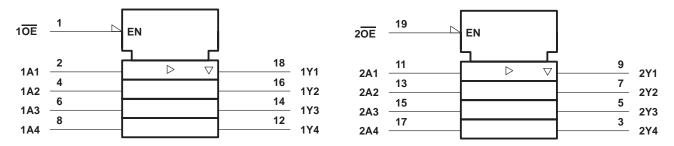


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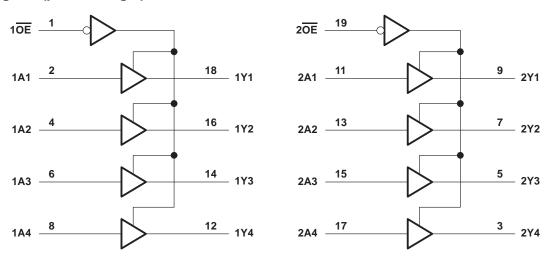


logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}		–0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)		–0.5 V to 4.6 V
Output voltage range, VO (see Notes 1 and 2)		0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)		
Output clamp current, I _{OK} (V _O < 0)		
Continuous output current, IO		±50 mA
Continuous current through V _{CC} or GND		±100 mA
Package thermal impedance, θ _{JA} (see Note 3)	: DGV package	146°C/W
	DW package	97°C/W
	NS package	100°C/W
	PW package	128°C/W
Storage temperature range, T _{stq}		–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.



recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
VCC	Supply voltage		1.65	3.6	V	
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}			
V_{IH}	High-level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		0.35 × V _{CC}		
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		V _{CC} = 2.7 V to 3.6 V		0.8		
VI	Input voltage		0	Vcc	V	
٧o	Output voltage		0	Vcc	V	
IOH I		V _{CC} = 1.65 V		-4		
	High-level output current	V _{CC} = 2.3 V		-12	mA	
		V _{CC} = 2.7 V		-12		
		V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
lOL	Low-level output current	V _{CC} = 2.3 V		12	mA	
		V _{CC} = 2.7 V		12	IIIA	
	V _{CC} = 3 V			24		
Δt/Δν	Input transition rise or fall rate			5	ns/V	
T _A	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS	Vcc	MIN	TYP†	MAX	UNIT
		I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} -0.	.2		
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			
		$I_{OH} = -6 \text{ mA}$	2.3 V	2			
VOH		2.3 V	1.7			V	
		I _{OH} = -12 mA	2.7 V	2.2			
			3 V	2.4			
		I _{OH} = -24 mA	3 V	2			
		I _{OL} = 100 μA	1.65 V to 3.6 V			0.2	
		I _{OL} = 4 mA	1.65 V			0.45	
\ \/ - ·		I _{OL} = 6 mA	2.3 V			0.4	
VOL	10.00	2.3 V			0.7	V	
	I _{OL} = 12 mA	2.7 V			0.4		
		I _{OL} = 24 mA	3 V			0.55	
lį		V _I = V _{CC} or GND	3.6 V			±5	μΑ
I _I (hold)		V _I = 0.58 V	1.65 V	§			
		V _I = 1.07 V	1.65 V	§			
		V _I = 0.7 V	2.3 V	45			
		V _I = 1.7 V	2.3 V	-45			μΑ
` ´		V _I = 0.8 V	3 V	75			
		V _I = 2 V	3 V	-75			
		V _I = 0 to 3.6 V [‡]	3.6 V			±500	
loz		$V_O = V_{CC}$ or GND	3.6 V			±10	μΑ
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V			10	μΑ
Δlcc		One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	3 V to 3.6 V			750	μА
Ci	Control inputs Data inputs	V _I = V _{CC} or GND	3.3 V		4.5 6		pF
Со	Outputs	V _O = V _{CC} or GND	3.3 V		8		pF

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
	(INFOT)	(001701)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
^t pd	А	Υ	§	1	3.1		3.1	1.1	2.8	ns
t _{en}	ŌĒ	Υ	§	1.5	5.4		5.3	1.5	4.5	ns
t _{dis}	ŌĒ	Y	§	1	4.1		4.4	1.7	4.2	ns

[§] This information was not available at the time of publication.



[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. ‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

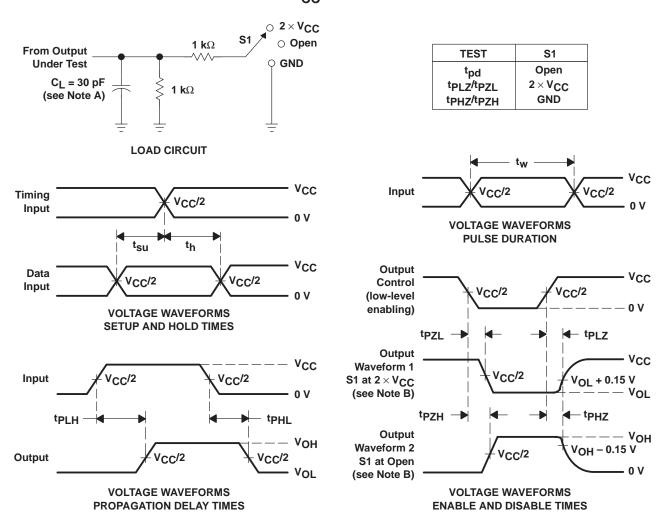
[§] This information was not available at the time of publication.

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V ± 0.2 V	V _{CC} = 3.3 V ± 0.3 V	UNIT	
		CONDITIONS	TYP	TYP	TYP	1 1	
Power dissipation capacitance	Outputs enabled	C _L = 0, f = 10 MHz	†	22	28	pF	
Cpd	C _{pd} per buffer/driver	Outputs disabled	CL = 0, 1 = 10 MH2	†	1.5	4	þг

[†]This information was not available at the time of publication.

PARAMETER MEASUREMENT INFORMATION V_{CC} = 1.8 V



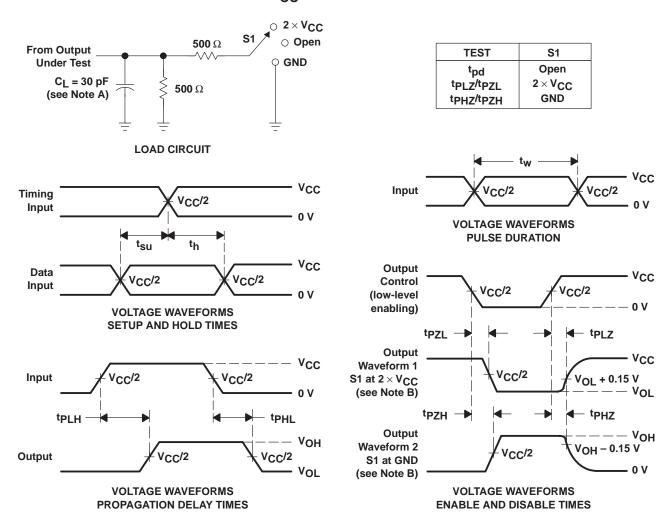
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2$ ns. $t_f \leq 2$ ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$

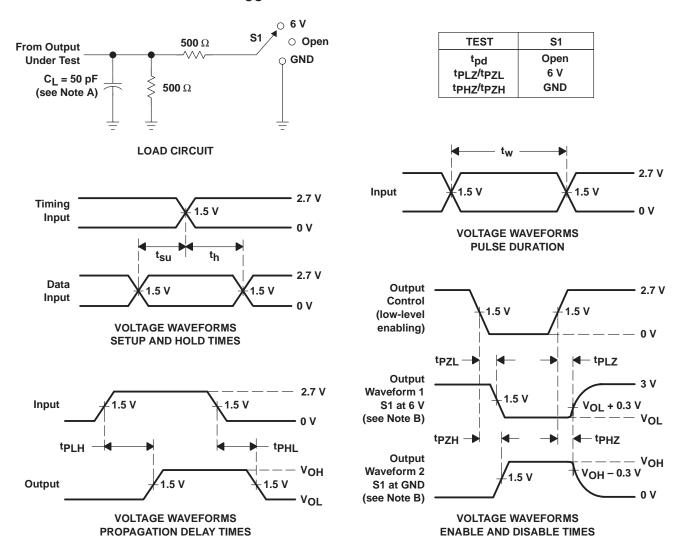


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2$ ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$, $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns,
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms



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